



Ref: F/820/1  
Tel.: 2737 2462

8 August 2011

President  
Hong Kong Computer Society  
LG1, No. 78 Tat Chee Avenue  
Kowloon Tong  
Kowloon

Dear Sir/Madam,

**Innovation and Technology Fund  
Guangdong-Hong Kong Technology Cooperation Funding Scheme and  
Tier 3 of the Innovation and Technology Support Programme  
Invitation for Applications**

I write to inform you that the 2011 Guangdong-Hong Kong Technology Cooperation Funding Scheme (TCFS) and the Tier 3 of the Innovation and Technology Support Programme (ITSP) of the Innovation and Technology Fund (ITF) are inviting funding applications.

The TCFS aims to strengthen cooperation between Hong Kong and Guangdong in technology development to support applied R&D projects which will facilitate the economic development in the Greater Pearl River Delta region, whereas the Tier 3 of ITSP supports projects which are more exploratory and forward-looking in nature.

We have adopted a new assessment framework and introduced new application form for TCFS. Further information on the TCFS, application form and Guide to Filling in the Application Form (the Guide) are available at the ITF website <http://www.itf.gov.hk>. Specific requirements of the 2011 TCFS, including the categories of projects and specific topics/themes for application, are set out in Appendix A of the Guide.

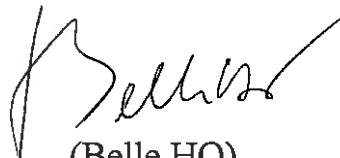
Applications of Category (A2) and Category C under TCFS and application of Tier 3 should be submitted to the ITF Secretariat (ITSP Section) either:

- (a) in triplicate (one original plus two duplicate copies) in person or by post. Please also kindly provide an electronic copy (preferably in MS Word 2003 or above); or
- (b) through the Innovation and Technology Commission Funding Administrative System ([https://www3.itf.gov.hk/?itf\\_lng=en](https://www3.itf.gov.hk/?itf_lng=en)).

Deadline for application is **16 September 2011**.

If you have any questions, please feel free to contact the ITF Secretariat at 2737 2229.

Yours sincerely,



(Belle HO)

for Commissioner for Innovation and Technology